

WAFER PROCESSING METHOD AND WAFER PROCESSING APPARATUS

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ABSTRACT OF THE DISCLOSURE

10 A wafer processing apparatus (10) has a grinder (80)
for grinding the back surface (22) of a wafer (20) on
whose front surface (21) a circuit pattern (C) has been
formed, and a die attachment paste applicator (30) for
applying die attachment paste on the entire back surface
15 of the wafer ground by the grinder. With this
arrangement, die attachment paste can be applied to a
wafer in a short period of time without using a film. The
die attachment paste applicator is either a spin-coater
(30A) that spin-coats die attachment paste supplied on
the back surface of a wafer, or a screen-printing device
20 (30B) that screen-prints die attachment paste on the back
surface of a wafer.

FIGURE 1